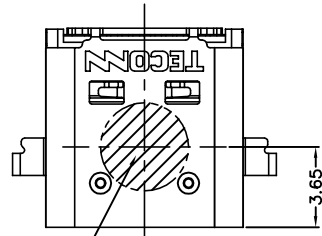
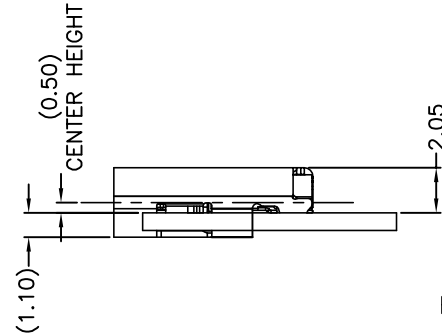
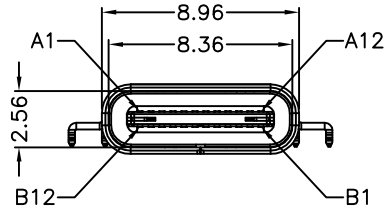


THE PART MEETS TECONN "GP001" COMPLIANCE NEW REV.



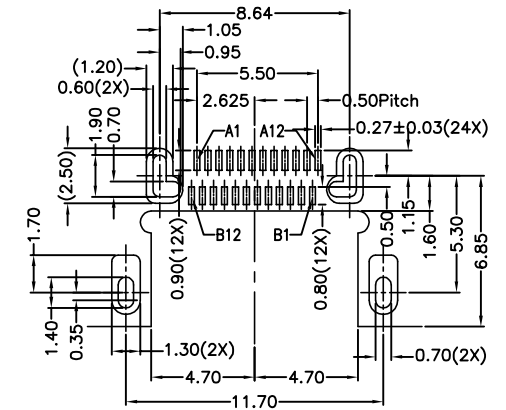
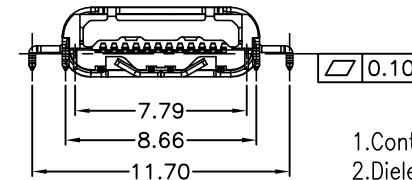
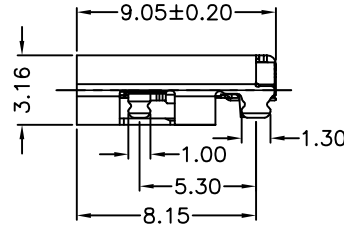
ADSORB AREA



A4Q2401-X-XX-R

F: 外壳有凸点
无接地片
塑胶原料

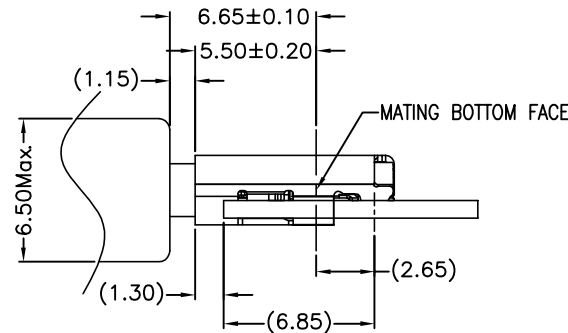
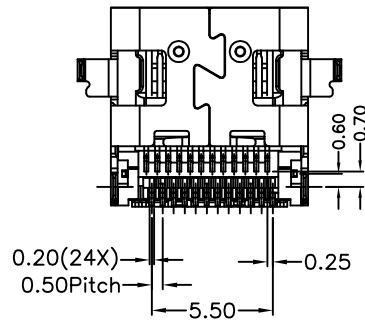
Mating Area plating
01: Au 1u"Min.
03: Au 3u"Min.
05: Au 5u"Min.
10: Au 10u"Min.
15: Au 15u"Min.
30: Au 30u"Min.



Applicable P.C.B Dimension
Tolerances:±0.05mm

- 1.Contact Resistance:40mOHM Max.;
- 2.Dielectric Withstanding Voltage:100V AC For 1 Minute;
- 3.Insulation Resistance:100M OHM Min.;
- 4.Mating And Unmating Force:
Mating Force: 5~20N
Unmating Force: 8~20N(0~1000cycle);
6~20N(1001~10000cycle);
- 5.Durability:10000 Cycles;

Item	Title	Material	Dispose	Remark
1	Shell	Stainless Steel	Ni:30u" Min.	
2	Mid Plate	Stainless Steel	Solder Tails: Matt Tin	
3	Top Contact	Copper Alloy	Mating Area: See P/N	
4	Bottom Contact	Copper Alloy	Solder Tails: Matt Tin	
5	Insulator	High Temperature Plastic	UL 94V-0	Black



REV	ECN NO	DESCRIPTION	DESIGN	DATE
X1	TE2019-0514	New Drawing	Bingo	2019/05/14

X. ± 0.30	APPD: Lebon Lee		TITLE: USB Type C Mid-Mount Dual-Row SMT Rec.	 泰康电子 TECONN	
.X ± 0.20	CHKD: /				
.XX ± 0.15	DR: Bingo		PART NO: A4Q2401-F-XX-R	CUSTOMER DRAWING	
.XXX±					
X* ± 2*	UNITS: mm	SCALE: 3:1	DWG NO: C-A4Q2401-F-XX-R	SHEET:10F1	
.X* ± 1.5*					
			REV: X1		